

C1812X331JHGACTU

Aliases (C1812X331JHGAC7800)

SMD Comm COG HV Flex, Ceramic, 330 pF, 5%, 3000 VDC, COG, SMD, MLCC, FT-CAP, Ultra-Stable, 1812



Click [here](#) for the 3D model.

Dimensions

Chip Size	1812
L	4.5mm +/-0.4mm
W	3.2mm +/-0.3mm
T	2.5mm +/-0.20mm
S	2.3mm MIN
B	0.7mm +/-0.35mm

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	500

General Information

Series	SMD Comm COG HV Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Ultra-Stable
Features	FT-CAP, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	false
AEC-Q200	No
Typical Component Weight	87 mg
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	330 pF
Measurement Condition	1MHz 1.0Vrms
Capacitance Tolerance	5%
Voltage DC	3000 VDC
Dielectric Withstanding Voltage	3600 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MHz 1.0Vrms
Dissipation Factor	0.1% 1MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms